

## N-Channel Power MOSFET

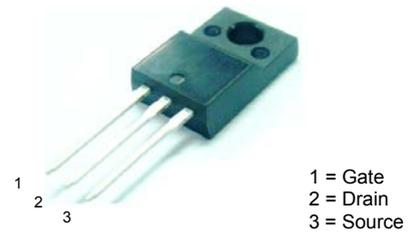
4.1A, 600V, 2.5Ω

### General Description

The N-Channel MOSFET is used an advanced termination scheme to provide enhanced voltage-blocking capability without degrading performance over time. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance. This device is well suited for high efficiency switched mode power suppliers, active power factor correction, electronic lamp ballasts based half bridge topology.

### Features

- Robust high voltage termination
- Avalanche energy specified
- Diode is characterized for use in bridge circuits
- Source to Drain diode recovery time comparable to a discrete fast recovery diode.

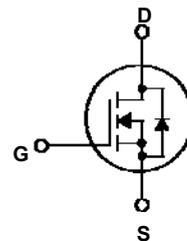


TO-220FP

### DEVICE MARKING DIAGRAM



L = Tak Cheong Logo  
 xxxy = Monthly Date Code  
 TFFXXXX = Device Type



### ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub>=25°C, unless otherwise noted )

Symbol	Parameter	Value	Units
V <sub>DSS</sub>	Drain- Source Voltage	600	V
V <sub>GSS</sub>	Gate-Source Voltage	± 30	V
I <sub>D</sub>	Drain Current	4.1	A
I <sub>DM</sub>	Drain Current Pulsed	16.4	A
P <sub>D</sub>	Power Dissipation (Note 2)	39	W
	Derating factor above 25°C	0.31	W/°C
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 1)	330	mJ
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 2)	7.3	mJ
T <sub>J</sub>	Operating Junction Temperature	150	°C
T <sub>stg</sub>	Storage Temperature Range	- 55 to +150	°C

### Notes:

1. L=30mH, I<sub>AS</sub>=4.4A, V<sub>DD</sub>=85V, R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25°C
2. Repetitive Rating: Pulse width limited by maximum junction temperature.

### THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case	3.18	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	62.5	°C/W

**ELECTRICAL CHARACTERISTICS**
**Off Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	600	--	--	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 600V, V_{GS} = 0V$	--	--	10	$\mu A$
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS} = 30V, V_{DS} = 0V$	--	--	100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS} = -30V, V_{DS} = 0V$	--	--	-100	nA

**On Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.0	--	4.0	V
$R_{DS(ON)}$	On-Resistance	$V_{GS} = 10V, I_D = 2.05A$	--	2.0	2.5	$\Omega$

**Dynamic Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$ $f = 1.0\text{MHz}$	--	570	741	pF
$C_{oss}$	Output Capacitance		--	64	83	pF
$C_{rss}$	Reverse Transfer Capacitance		--	14	18	pF

**Switching Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 300V, I_D = 4.1A,$ $R_G = 25\Omega$ (Note 3 & 4)	--	25	32	nS
$t_r$	Turn-On Rise Time		--	54	70	nS
$t_{d(off)}$	Turn-Off Delay Time		--	120	157	nS
$t_f$	Turn-Off Fall Time		--	34	45	nS
$Q_g$	Total Gate Charge	$V_{DS} = 480V, I_D = 4.1A,$	--	19	25	nC
$Q_{gs}$	Gate-Source Charge	$V_{GS} = 10V$	--	2.9	--	nC
$Q_{gd}$	Gate-Drain Charge	(Note 3 & 4)	--	8.2	--	nC

**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_S$	Maximum Continuous Drain-Source Diode Forward Current		--	--	4.1	A
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current		--	--	16.4	A
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0V, I_S = 4.1A$	--	--	1.4	V
$T_{rr}$	Reverse Recovery Time	$V_{GS} = 0V, I_S = 4.1A,$ $dI_F / dt = 100A/\mu S$	--	560	--	nS
$Q_{rr}$	Reverse Recovery Charge	(Note 3)	--	1.78	--	$\mu C$

**Notes:**

- Pulse Test: Pulse width < 300 $\mu s$ , Duty cycle  $\leq 2\%$ .
- Basically not affected by working temperature.

TYPICAL CHARACTERISTICS

Fig 1. On-State Characteristics

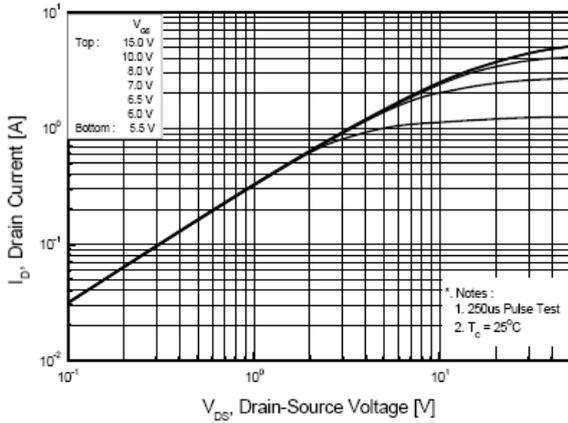


Fig 2. Transfer Characteristics

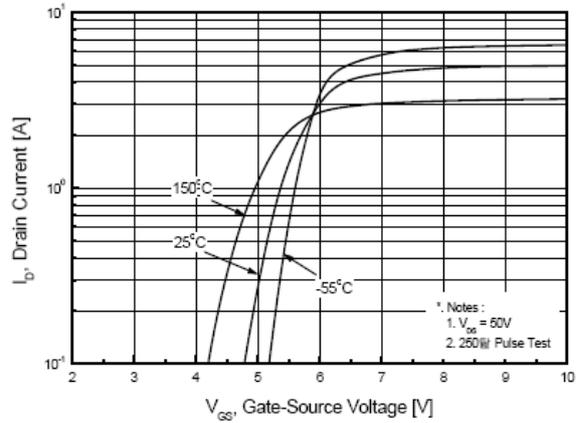


Fig 3. On Resistance Variation vs. Drain Current and Gate Voltage

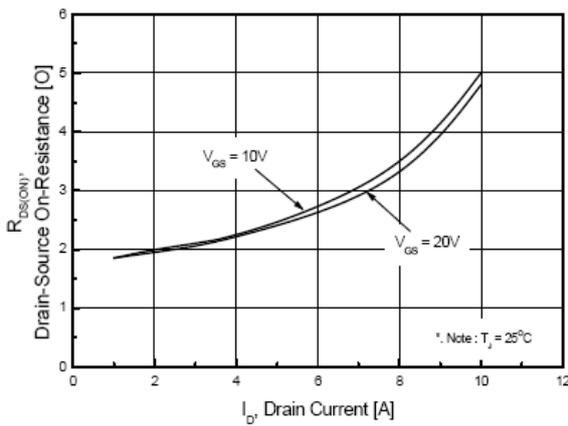


Fig 4. On State Current vs. Allowable Case Temperature

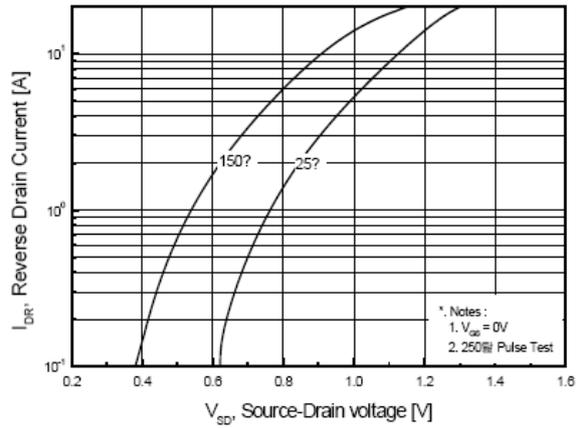


Fig 5. Capacitance Characteristics (Non-Repetitive)

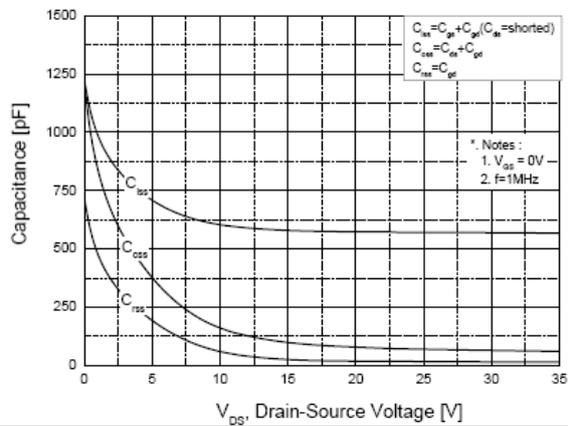
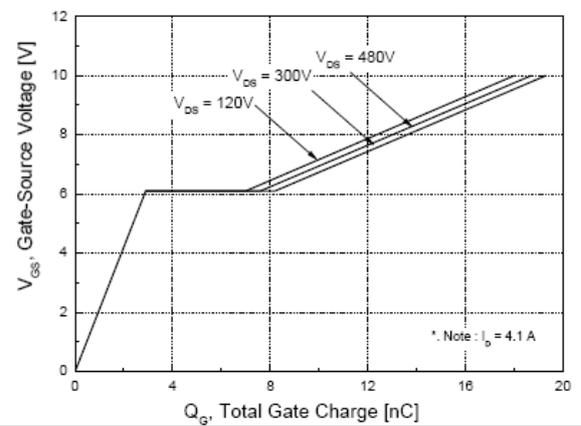
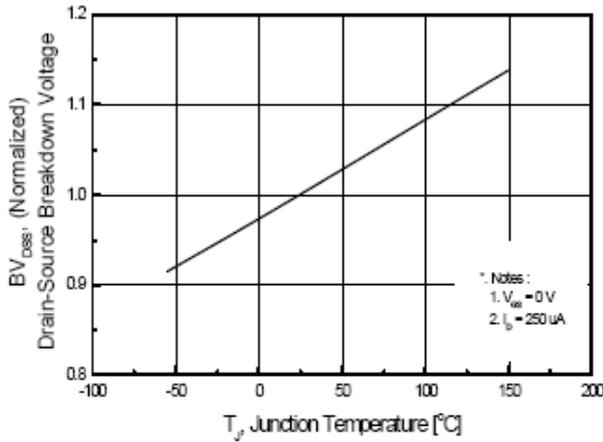


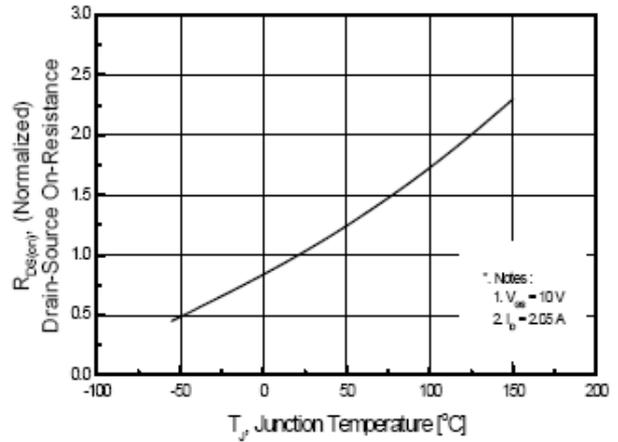
Fig 6. Gate Charge Characteristics



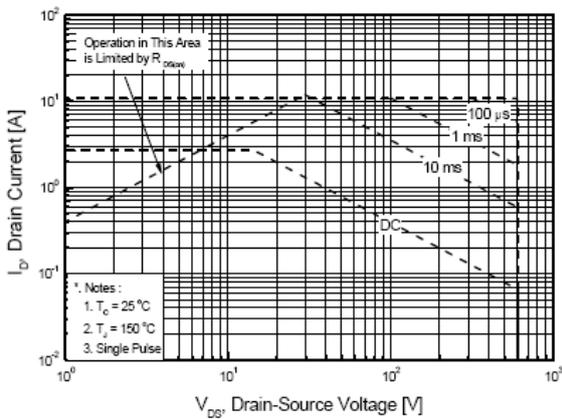
**Fig 7. Breakdown Voltage Variation vs. Junction Temperature**



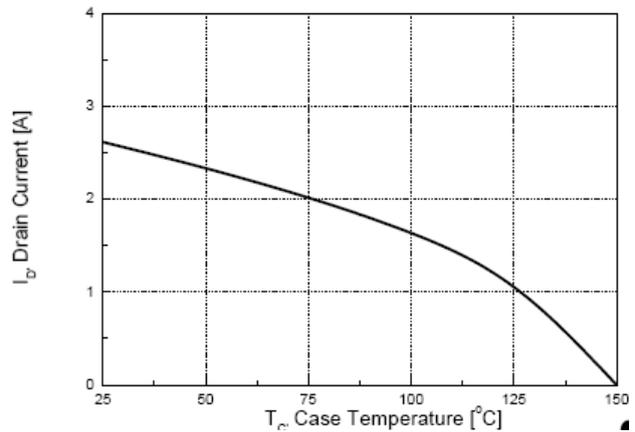
**Fig 8. On-Resistance Variation vs. Junction Temperature**



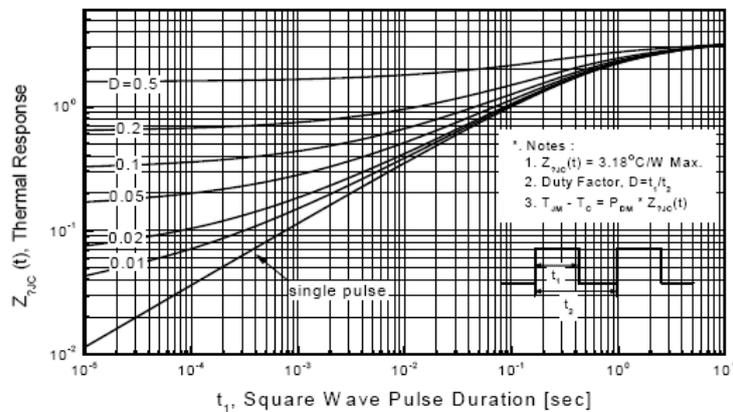
**Fig 9. Maximum Safe Operating Area (TO-220F)**



**Fig 10. Maximum Drain Current vs. Case Temperature. (TO220F)**



**Fig 11. Transient Thermal Response Curve (TO220F)**



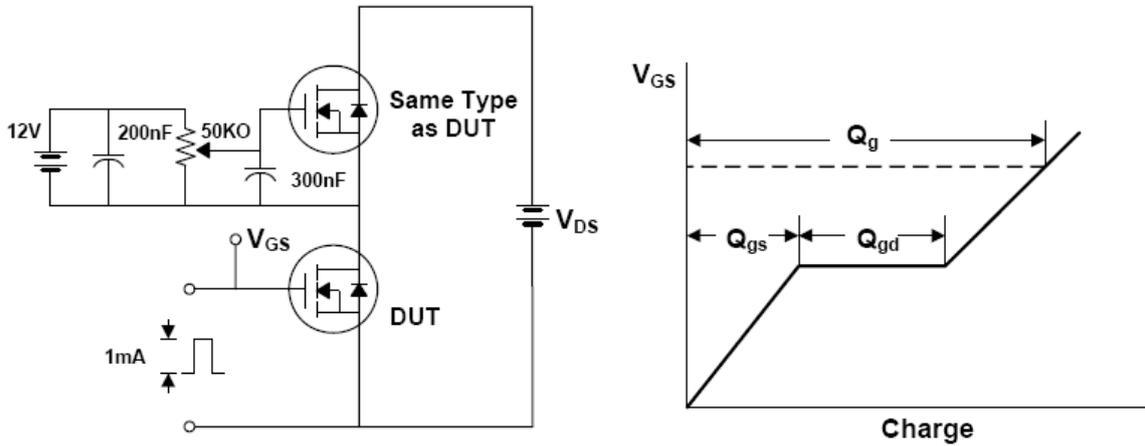
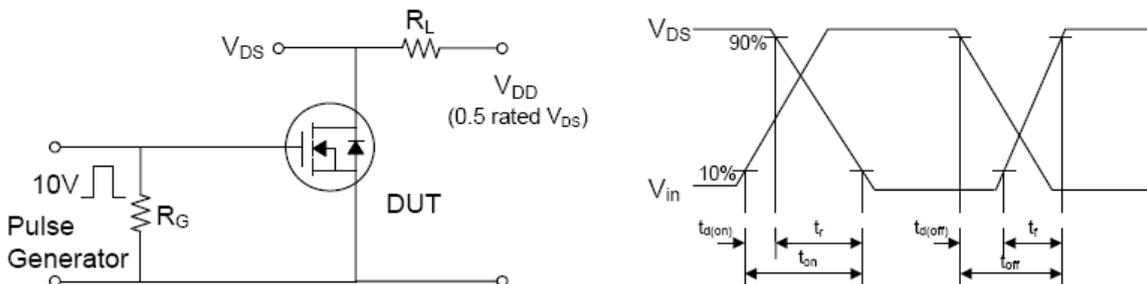
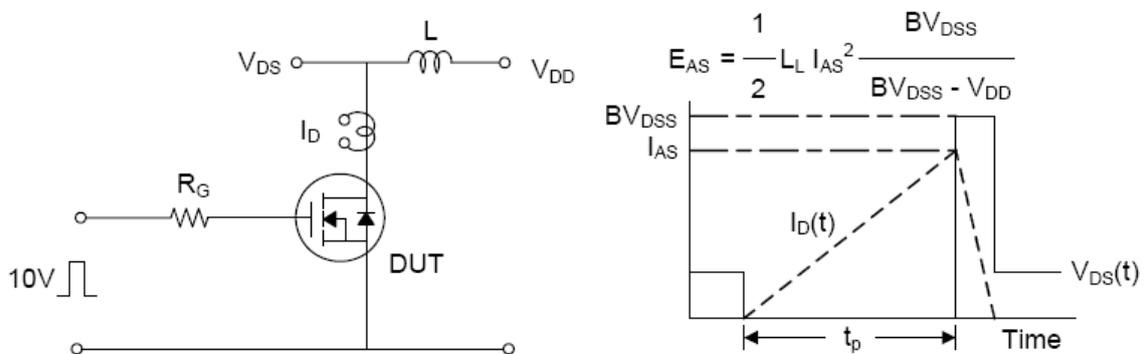
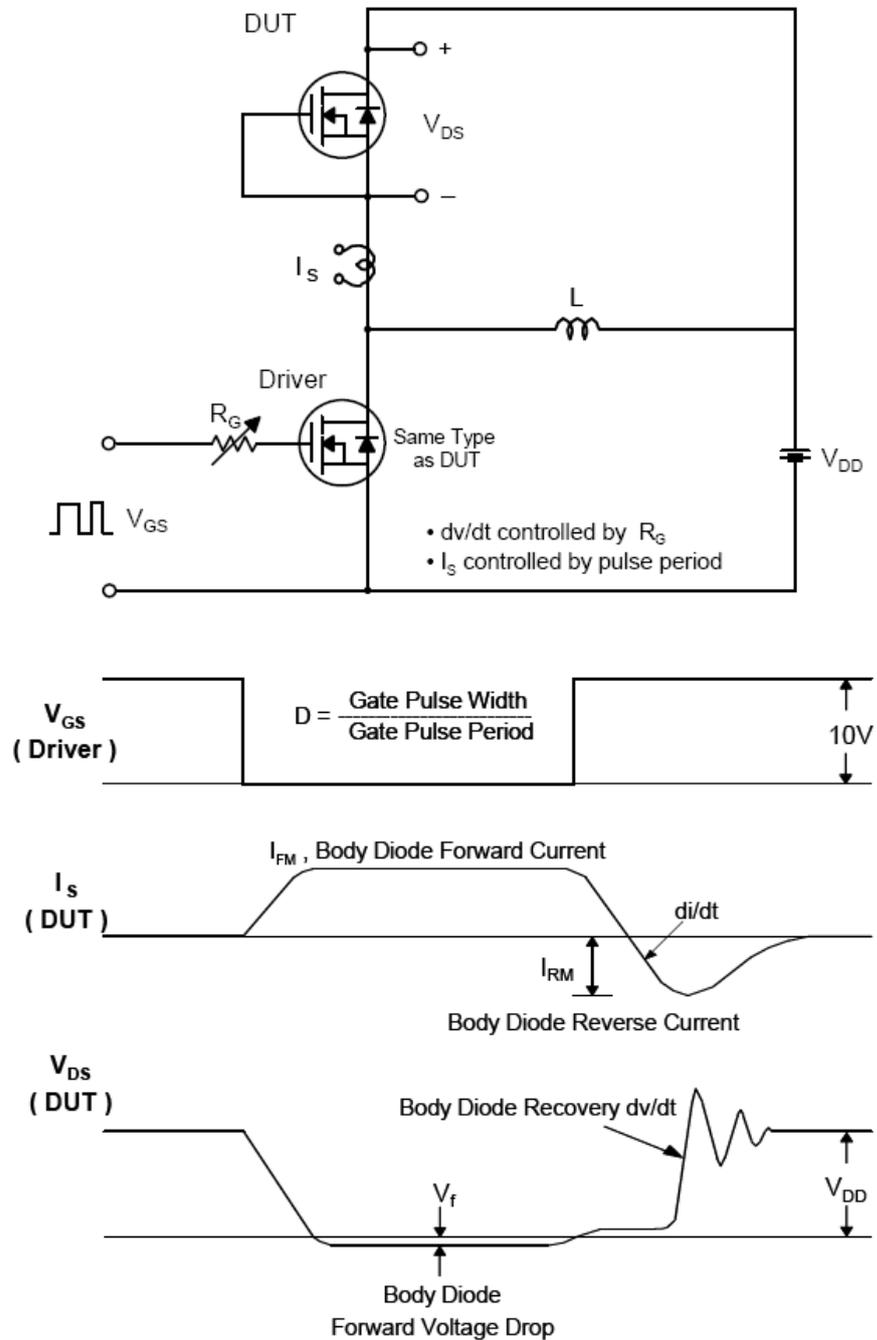
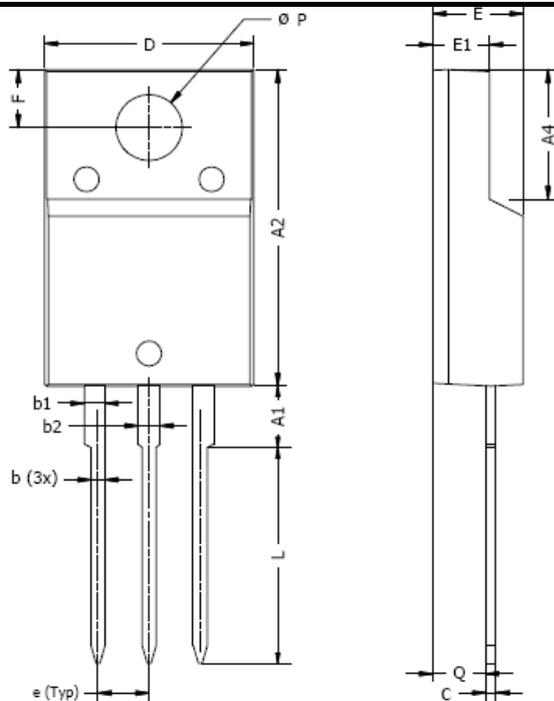
**Fig. 12. Gate Charge Test Circuit & Waveforms**

**Fig 13. Switching Time Test Circuit & Waveforms**

**Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms**


Fig. 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



**TO220FP PACKAGE OUTLINE**


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A1	2.7	3.3	0.106	0.130
A2	15.0	15.7	0.591	0.618
A4	6.2	6.6	0.244	0.260
b	0.5	0.9	0.020	0.035
b1	0.9	1.2	0.035	0.047
b2	1.0	1.2	0.039	0.047
c	0.4	0.6	0.016	0.024
D	9.8	10.3	0.386	0.406
e	2.34	2.74	0.092	0.108
E	4.3	4.6	0.169	0.181
E1	2.5	2.9	0.098	0.114
F	2.6	3.0	0.102	0.118
L	10.3	10.7	0.406	0.421
$\phi P$	3.0	3.4	0.118	0.134
Q	2.3	2.7	0.091	0.106

**Note:** Single Gauge

## **NOTICE**

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